

### REMARKS

Claims 1 to 5, 7 to 11 and 19 to 24 are pending in this application of which claims 1 and 11 are the independent claims. Favorable reconsideration and further examination are respectfully requested.

Initially, the Examiner rejected the drawings because, in FIG. 3A, reference 26b was included twice. Also, in FIG. 8, reference 40f should be pointing to the solder bump and reference 14b should be pointing to the dielectric region. Accordingly, Applicants have amended the drawings in accordance with the Examiner's recommendations.

The Examiner has objected to the specification because the term "water" should be "wafer" and the term "solder balls 44a-44f" should be "solder balls 40a-40f." Accordingly Applicants have amended the specification in accordance with the Examiner's recommendations.

Turning to the art rejections, claims 1 to 11 were rejected under 35. U.S.C § 102 over Camenforte et al. (U.S. Patent No. 6,537,848). As shown above, Applicants have amended claims 1 and 11 to define the invention in greater clarity. Applicants traverse the rejection of the remaining claims except for claim 7 which was amended for antecedents.

Independent claim 1 is directed to a semiconductor structure. The semiconductor structure includes a semiconductor chip that has an edge and a surface. The structure also includes a contact pad disposed on the surface of the semiconductor chip. The structure further includes a conductive layer disposed on the surface of the semiconductor chip and in contact

with the contact pad. The conductive layer has a portion that extends beyond the edge of the semiconductor chip.

The applied art is not understood to disclose or suggest the foregoing features of claim 1. In particular, Camenforte does not disclose or suggest “a conductive layer disposed on the surface of the semiconductor chip and in contact with the contact pad.”

More specifically, Camenforte describes copper traces 78 that do not contact the contact pad. Indeed, the copper traces 78 are in contact with one surface of the semiconductor and the contact pad 80 is in contact with the opposite surface and therefore neither are ever in contact with each other (see FIG. 4 of Camenforte). Since Camenforte does not disclose or suggest a conductive layer that is in contact with the contact pad, Applicants submit that claim 1 is patentable over Camenforte.

Independent claim 11 is directed to a semiconductor structure. The semiconductor structure includes a semiconductor chip that has a surface and an edge. The structure also includes a contact pad disposed on the surface of the semiconductor chip. The structure further includes a front layer that has a first portion disposed on the surface of the semiconductor chip and a second portion that extends beyond the edge of the chip.

The applied art is not understood to disclose or suggest the foregoing features of claim 1. In particular, Camenforte does not disclose or suggest “a contact pad disposed on the surface of the semiconductor chip” and “a front layer, having a first portion disposed on the surface of the semiconductor chip.”

More specifically, Camenforte describes copper traces 78 that are in contact with one surface of the semiconductor chip and contact pad 80 that is in contact with an opposite surface (see FIG. 4 of Camenforte). Since Camenforte does not disclose or suggest that the conductive layer and the contact pad are disposed on the same surface of the semiconductor chip, Applicants submit that claim 11 is patentable over Camenforte.


In view of the foregoing amendments and remarks, Applicants submit that the entire application is now in condition for allowance. Such action is respectfully requested at the Examiner's earliest convenience.

All correspondence should be directed to the below address. Applicants' attorney can be reached by telephone at the number shown below.

No fee is believed to be due for this Response; however, if any fees are due, please apply such fees to Deposit Account No. 06-1050 referencing Attorney Docket 13292-006001.

Respectfully submitted,

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